REMARKS

Applicants request that the Examiner enter the amendment prior to examining the application. In the specification, paragraphs [0016], [0028], [0035], [0036], [0040], [0041], [0044], [0045], [0054], [0056], and [0063] have been amended to correct informalities. Claims 1-7, 15, 17-27, and 29-33 have been amended. These amendments are not presented to distinguish a reference, thus, the claims as amended are entitled to a full range of equivalents if not previously amended to distinguish a reference. In the drawings, Figure 1 has been amended to include previously omitted element label 100 Applicants believe that this amendment does not introduce new matter. Entry of the amendment is respectfully requested.

Respectfully submitted,

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In the Drawings:

The attached sheet of drawings includes changes to Figure 1 and replaces the original sheet including Figure 1.

In Figure 1, previously omitted element label 100 has been inserted.

Attached is 1 sheet of formal drawings showing the abovementioned change and a marked-up copy of the original sheet. Please amend and admit Figure 1 as shown in the attached sheet.

Attachment:

Replacement Sheet

Annotated Sheet Showing Change

ANNOTATED SHEET
AMAT/8327/ETCH/SILICON/JB
10/690,318
October 6 ATTY DKT. NO.: U.S. SERIAL NO.: **CONFIRMATION: 1763** October 21, 2003
APPLIED MATERIALS, INC.
Method for Controlling Accuracy and Repeatability of an Etch Process FILED: APPLICANT: TITLE: INVENTOR: FIGURE 1 1/6 100 _ 101 **START** - 102 FORM PATTERNED ETCH MASK MEASURE DIMENSIONS OF ELEMENTS _ 104 OF PATTERNED ETCH MASK TRIM PATTERNED ETCH MASK 106 PERFORM ETCH PROCESS 108 TRIM OR REMOVE AT LEAST A 110 117 PORTION OF POST-ETCH RESIDUE **CALCULATE** 112 -ADJUSTMENT FOR **ETCH RECIPE** MEASURE DIMENSIONS OF - 116 **ETCHED STRUCTURES** CALCULATE ADJUSTMENT FOR - 114 TRIMMING RECIPE DOES ETCH PROCESS **NEED ADJUSTMENT?** YES NO

FIG. 1

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END
